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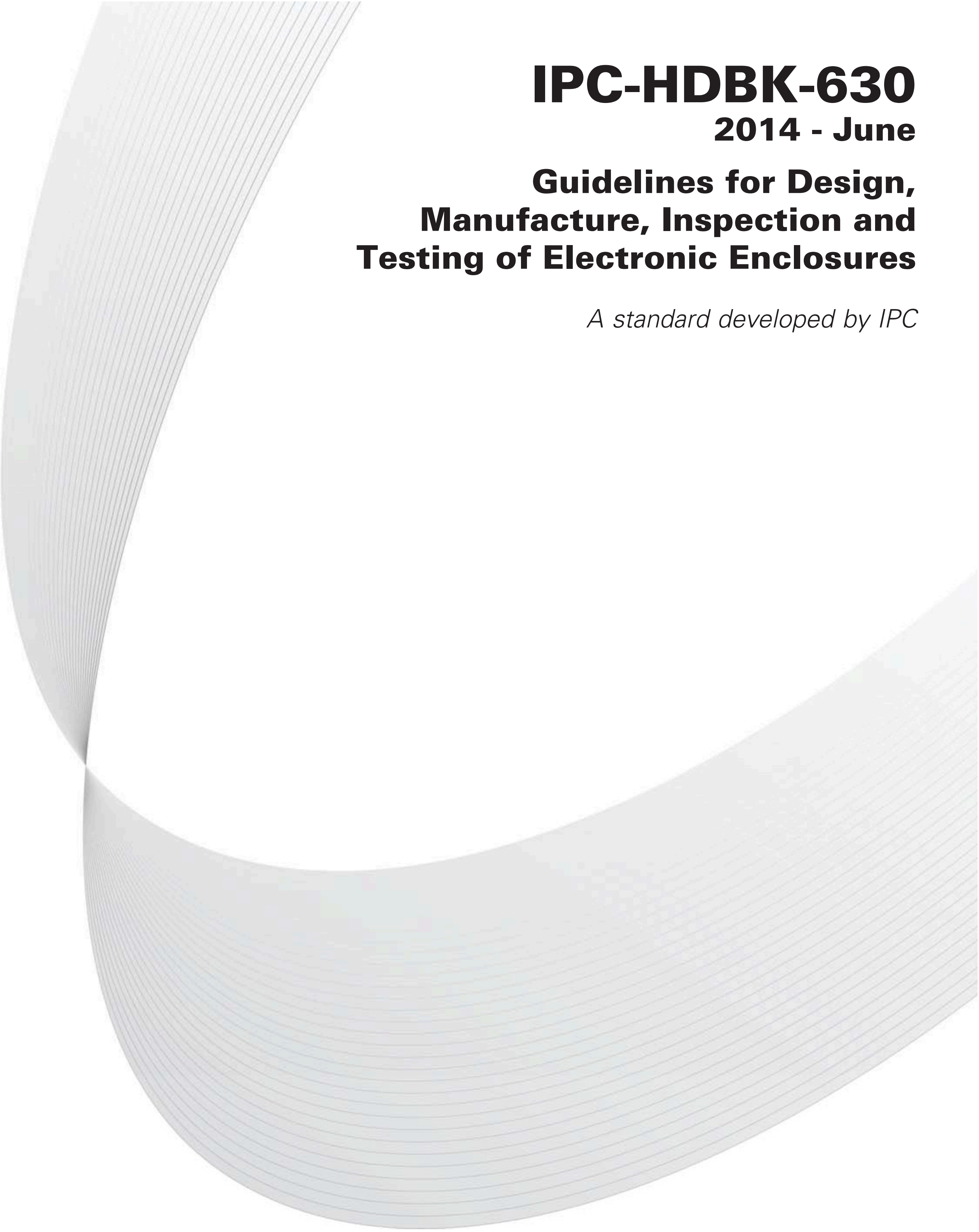
Guidelines for Design, Manufacture, Inspection and Testing of Electronic Enclosures

A standard developed by IPC



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Guidelines for Design, Manufacture, Inspection and Testing of Electronic Enclosures Assembly

Developed by the Requirements for Structural Enclosure Task Group (7-31j) of the Product Assurance Committee (7-30) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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Acknowledgment

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